ON Semiconductor

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Single Non-Inverting Buffer with Open Drain Output

MC74VHC1G07, MC74VHC1GT07

The MC74VHC1G07 / MC74VHC1GT07 is a single non-inverting buffer with open drain output in tiny footprint packages. The MC74VHC1G07 has CMOS-level input thresholds while the MC74VHC1GT07 has TTL-level input thresholds.

The input structures provide protection when voltages up to 5.5 V are applied, regardless of the supply voltage. This allows the device to be used to interface 5 V circuits to 3 V circuits. The output structures also provide protection when $V_{\rm CC}=0$ V and when the output voltage exceeds $V_{\rm CC}$. These input and output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

Features

- Designed for 2.0 V to 5.5 V V_{CC} Operation
- 3.5 ns t_{PD} at 5 V (typ)
- Inputs/Outputs Over-Voltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 8 mA at 3.0 V
- Available in SC-88A, SC-74A, TSOP-5, SOT-553, SOT-953 and UDFN6 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

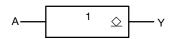
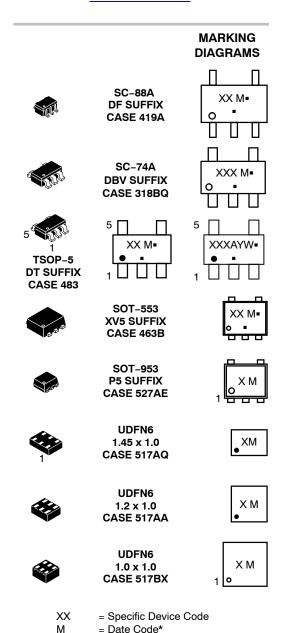


Figure 1. Logic Symbol



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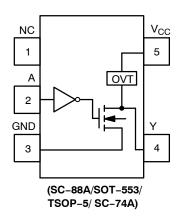
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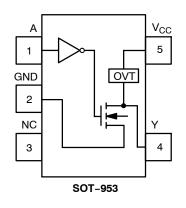


ORDERING INFORMATION

= Pb-Free Package
 (Note: Microdot may be in either location)

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.





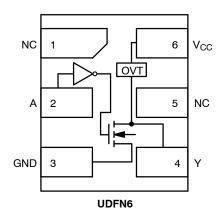


Figure 2. Pinout (Top View)

PIN ASSIGNMENT

(SC-88A/SOT-553/ TSOP-5/SC-74A)

| Pin | Function |
|-----|-----------------|
| 1 | NC |
| 2 | Α |
| 3 | GND |
| 4 | Υ |
| 5 | V _{CC} |

PIN ASSIGNMENT (SOT-953)

| Pin | Function |
|-----|-----------------|
| 1 | А |
| 2 | GND |
| 3 | NC |
| 4 | Y |
| 5 | V _{CC} |

PIN ASSIGNMENT (UDFN)

| Pin | Function |
|-----|-----------------|
| 1 | NC |
| 2 | А |
| 3 | GND |
| 4 | Y |
| 5 | NC |
| 6 | V _{CC} |

FUNCTION TABLE

| A Input | Y Output | | | |
|---------|----------|--|--|--|
| L | L | | | |
| Н | Z | | | |

MAXIMUM RATINGS

| Symbol | Characteristic | cs | Value | Unit |
|-------------------------------------|--|---|---|------|
| V _{CC} | DC Supply Voltage SC-74A, SC- | TSOP-5, SC-88A (NLV) 88A, UDFN6, SOT-553, SOT-953 | -0.5 to +7.0 -0.5 to +6.5 | V |
| V _{IN} | DC Input Voltage SC-74A, SC- | TSOP-5, SC-88A (NLV) 88A, UDFN6, SOT-553, SOT-953 | -0.5 to +7.0 -0.5 to +6.5 | V |
| V _{OUT} | DC Output Voltage TSOP-5, SC-88A (NLV) | Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V) | -0.5 to V _{CC} + 0.5 -0.5 to +7.0 -0.5 to +7.0 | V |
| | DC Output Voltage SC-74A, SC-88A, UDFN6, SOT-553, SOT-9 | -0.5 to V _{CC} + 0.5 -0.5 to +6.5 -0.5 to +6.5 | V | |
| I _{IK} | DC Input Diode Current | V _{IN} < GND | -20 | mA |
| I _{OK} | DC Output Diode Current | V _{OUT} < GND | -20 | mA |
| l _{OUT} | DC Output Source/Sink Current | | ±25 | mA |
| I _{CC} or I _{GND} | DC Supply Current per Supply Pin or Ground | Pin | ±50 | mA |
| T _{STG} | Storage Temperature Range | | -65 to +150 | °C |
| TL | Lead Temperature, 1 mm from Case for 10 sec | cs | 260 | °C |
| T_J | Junction Temperature Under Bias | | +150 | °C |
| $\theta_{\sf JA}$ | Thermal Resistance (Note 2) | SC-88A SC-74A SOT-553 SOT-953 UDFN6 | 377 320 324 254 154 | °C/W |
| P _D | Power Dissipation in Still Air | SC-88A SC-74A SOT-553 SOT-953 UDFN6 | 332 390 386 491 812 | mW |
| MSL | Moisture Sensitivity | | Level 1 | - |
| F _R | Flammability Rating | Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in | - |
| V _{ESD} | ESD Withstand Voltage (Note 3) | Human Body Model Charged Device Model | 2000 1000 | V |
| I _{Latchup} | Latchup Performance (Note 4) | | ±100 | mA |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.

2. Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.

3. HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.

4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

| Symbol | | Characteristics | Min | Max | Unit |
|---------------------------------|----------------------------|--|------------------|-------------------------------|------|
| V _{CC} | Positive DC Supply Voltage | | 2.0 | 5.5 | V |
| V _{IN} | DC Input Voltage | | 0 | 5.5 | V |
| V _{OUT} | DC Output Voltage | TSOP-5, SC-88A (NLV) | 0 | V _{CC} | V |
| | DC Output Voltage | SC-74A, SC-88A, UDFN6, SOT-553, SOT-953 Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode ($V_{\rm CC}$ = 0 V) | 0 0 0 | V _{CC} 5.5 5.5 | |
| T _A | Operating Temperature Ran | -55 | +125 | °C | |
| t _r , t _f | Input Rise and Fall Time | TSOP-5, SC-88A (NLV) V _{CC} = 3.0 V to 3.6 V V _{CC} = 4.5 V to 5.5 V | 0 | 100 20 | ns/V |
| | Input Rise and Fall Time | SC-74A, SC-88A, UDFN6, SOT-553, SOT-953 $V_{CC}=2.0\ V$ $V_{CC}=2.3\ V\ to\ 2.7\ V$ $V_{CC}=3.0\ V\ to\ 3.6\ V$ $V_{CC}=4.5\ V\ to\ 5.5\ V$ | 0 0 0 0 | 20 20 10 5 | |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS (MC74VHC1G07)

| | | Test | Vcc | 1 | Γ _A = 25° | С | -40°C ≤ | Γ _A ≤ 85°C | -55°C ≤ T | _ _A ≤ 125°C | |
|------------------|-----------------------------------|--|---------------------------------|------------------|-----------------------------|-----------------------------------|---------|-----------------------------------|------------------|-----------------------------------|------|
| Symbol | Parameter | Conditions | (V) | Min | Тур | Max | Min | Max | Min | Max | Unit |
| V _{IH} | High-Level Input | | 2.0 | 1.5 | _ | - | 1.5 | _ | 1.5 | - | V |
| | Voltage | | 3.0 | 2.1 | _ | - | 2.1 | - | 2.1 | - | |
| | | | 4.5 | 3.15 | - | - | 3.15 | _ | 3.15 | - | |
| | | | 5.5 | 3.85 | - | - | 3.85 | _ | 3.85 | - | |
| V_{IL} | Low-Level Input | | 2.0 | - | _ | 0.5 | - | 0.5 | - | 0.5 | V |
| | Voltage | | 3.0 | - | _ | 0.9 | - | 0.9 | - | 0.9 |] |
| | | | 4.5 | - | _ | 1.35 | - | 1.35 | - | 1.35 | |
| | | | 5.5 | - | _ | 1.65 | - | 1.65 | - | 1.65 |] |
| V _{OL} | Low-Level Output Voltage | $\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 4 \text{ mA} \\ &I_{OL} = 8 \text{ mA} \end{aligned}$ | 2.0 3.0 4.5 3.0 4.5 | - - - - | 0.0 0.0 0.0 - - | 0.1 0.1 0.1 0.36 0.36 | | 0.1 0.1 0.1 0.44 0.44 | - - - - | 0.1 0.1 0.1 0.52 0.52 | > |
| I _{IN} | Input Leakage Current | V _{IN} = 5.5 V or GND | 2.0 to 5.5 | - | _ | ±0.1 | - | ±1.0 | _ | ±1.0 | μΑ |
| I _{OZ} | 3-State Output Leakage Current | V _{OUT} = 0 V to 5.5 V | 5.5 | _ | - | ±0.25 | - | ±2.5 | - | ±2.5 | μΑ |
| I _{OFF} | Power Off Leakage Current | V _{IN} = 5.5 V or V _{OUT} = 5.5 V | 0 | _ | _ | 1.0 | - | 10 | - | 10 | μΑ |
| I _{CC} | Quiescent Supply Current | V _{IN} = V _{CC} or GND | 5.5 | _ | _ | 1.0 | ı | 20 | _ | 40 | μΑ |

DC ELECTRICAL CHARACTERISTICS (MC74VHC1GT07)

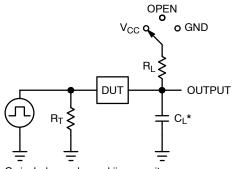
| | Test | | v _{cc} | 7 | T _A = 25° | С | -40°C ≤ 7 | Γ _A ≤ 85°C | -55°C ≤ T | _A ≤ 125°C | |
|------------------|--|--|---------------------------------|------------------|-----------------------------|-----------------------------------|------------------|-----------------------------------|------------------|-----------------------------------|----------|
| Symbol | Parameter | Conditions | (V) | Min | Тур | Max | Min | Max | Min | Max | Unit |
| V _{IH} | High-Level Input | | 2.0 | 1.0 | _ | | 1.0 | - | 1.0 | _ | ٧ |
| | Voltage | | 3.0 | 1.4 | - | | 1.4 | _ | 1.4 | - | |
| | | | 4.5 | 2.0 | - | | 2.0 | - | 2.0 | _ | |
| | | | 5.5 | 2.0 | - | | 2.0 | - | 2.0 | - | |
| V_{IL} | Low-Level Input | | 2.0 | - | _ | 0.28 | ı | 0.28 | - | 0.28 | ٧ |
| | Voltage | | 3.0 | - | - | 0.45 | ı | 0.45 | - | 0.45 | |
| | | | 4.5 | - | - | 0.8 | ı | 0.8 | - | 0.8 | |
| | | | 5.5 | _ | _ | 0.8 | 1 | 0.8 | - | 0.8 | |
| V _{OL} | Low-Level Output Voltage | $\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 4 m\text{A} \\ &I_{OL} = 8 m\text{A} \end{aligned}$ | 2.0 3.0 4.5 3.0 4.5 | - - - - | 0.0 0.0 0.0 - - | 0.1 0.1 0.1 0.36 0.36 | - - - - | 0.1 0.1 0.1 0.44 0.44 | - - - - | 0.1 0.1 0.1 0.52 0.52 | V |
| I _{IN} | Input Leakage Cur- rent | V _{IN} = 5.5 V or GND | 2.0 to 5.5 | _ | _ | ±0.1 | - | ±1.0 | _ | ±1.0 | μΑ |
| l _{OZ} | 3-State Output Leakage Current | V _{OUT} = 0 V to 5.5 V | 5.5 | _ | _ | ±0.25 | - | ±2.5 | - | ± 2.5 | μΑ |
| l _{OFF} | Power Off Leakage Current | V _{IN} = 5.5 V or V _{OUT} = 5.5 V | 0 | _ | _ | 1.0 | - | 10 | - | 10 | μΑ |
| I _{CC} | Quiescent Supply Current | V _{IN} = V _{CC} or GND | 5.5 | - | - | 1.0 | - | 20 | _ | 40 | μΑ |
| I _{CCT} | Increase in Quies- cent Supply Current per Input Pin | One Input: V _{IN} = 3.4 V; Other Input at V _{CC} or GND | 5.5 | - | - | 1.35 | - | 1.5 | - | 1.65 | mA |

AC ELECTRICAL CHARACTERISTICS

| | | | | T | A = 25° | С | -40°C ≤ 7 | Γ _A ≤ 85°C | -55°C ≤ T | A ≤ 125°C | |
|------------------|-----------------------------|---|---------------------|-----|---------|------|-----------|-----------------------|-----------|-----------|------|
| Symbol | Parameter | Conditions | V _{CC} (V) | Min | Тур | Max | Min | Max | Min | Max | Unit |
| t _{PZL} | Propagation Delay, | C _L = 15 pF | 3.0 to 3.6 | - | 5.0 | 7.1 | - | 8.5 | - | 10.0 | ns |
| | A to Y (Figures 3 and 4) | C _L = 50 pF | | - | 7.5 | 10.6 | - | 12.0 | _ | 14.5 | |
| | (i. igaroo o ana i) | C _L = 15 pF | 4.5 to 5.5 | - | 3.8 | 5.5 | - | 6.5 | _ | 8.0 | |
| | | C _L = 50 pF | | - | 5.3 | 7.5 | - | 8.5 | _ | 10.0 | |
| t _{PLZ} | Propagation Delay, | C _L = 15 pF | 3.0 to 3.6 | - | 6.5 | 9.7 | - | 11.5 | _ | 12.5 | ns |
| | A to Y (Figures 3 and 4) | C _L = 50 pF | | - | 7.5 | 10.6 | - | 15.0 | _ | 14.5 | |
| | , | C _L = 15 pF | 4.5 to 5.5 | - | 4.8 | 6.8 | - | 8.0 | _ | 9.0 | |
| | | C _L = 50 pF | | - | 5.3 | 7.5 | - | 10.0 | _ | 120.0 | |
| C _{IN} | Input Capacitance | | | - | 4.0 | 10 | - | 10 | _ | 10 | pF |
| C _{OUT} | Output Capacitance | Output in High Impedance State | | - | 6.0 | - | - | - | - | - | pF |

| Ī | | | Typical @ 25°C, V _{CC} = 5.0 V | |
|---|----------|--|---|----|
| | C_{PD} | Power Dissipation Capacitance (Note 5) | 8.0 | pF |

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.



| Test | Switch Position | C _L , pF | R_L, Ω |
|-------------------------------------|--------------------|------------------------------|---------------|
| t _{PLH} / t _{PHL} | Open | See AC Characteristics Table | Х |
| t _{PLZ} / t _{PZL} | V _{CC} | | 1 k |
| t _{PHZ} / t _{PZH} | GND | | 1 k |

X = Don't Care

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$ f = 1 MHz

Figure 3. Test Circuit

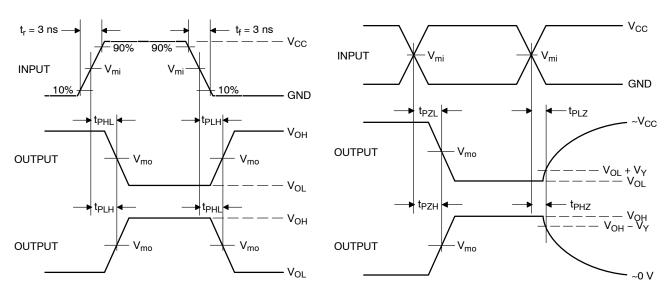


Figure 4. Switching Waveforms

| | | V _m | | |
|---------------------|---------------------|-------------------------------------|---|--------------------|
| V _{CC} , V | V _{mi} , V | t _{PLH} , t _{PHL} | t_{PZL} , t_{PLZ} , t_{PZH} , t_{PHZ} | V _Y , V |
| 3.0 to 3.6 | V _{CC} /2 | V _{CC} /2 | V _{CC} /2 | 0.3 |
| 4.5 to 5.5 | V _{CC} /2 | V _{CC} /2 | V _{CC} /2 | 0.3 |

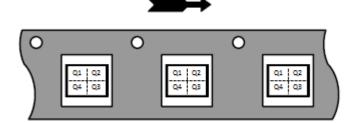
ORDERING INFORMATION

| Device | Packages | Specific Device Code | Pin 1 Orientation (See below) | Shipping [†] |
|--|-------------------------|----------------------|-------------------------------|-----------------------|
| MC74VHC1G07DFT1G | SC-88A | V7 | Q2 | 3000 / Tape & Reel |
| MC74VHC1G07DFT2G | SC-88A | V7 | Q4 | 3000 / Tape & Reel |
| NLVVHC1G07DFT1G* | SC-88A | V7 | Q2 | 3000 / Tape & Reel |
| NLVVHC1G07DFT2G* | SC-88A | V7 | Q4 | 3000 / Tape & Reel |
| MC74VHC1GT07DFT1G (In Development) | SC-88A | TBD | Q4 | 3000 / Tape & Reel |
| MC74VHC1GT07DFT2G (In Development) | SC-88A | TBD | Q2 | 3000 / Tape & Reel |
| MC74VHC1G07DBVT1G | SC-74A | V7 | Q4 | 3000 / Tape & Reel |
| MC74VHC1GT07DBVT1G (In Development) | SC-74A | TBD | Q4 | 3000 / Tape & Reel |
| MC74VHC1G07DTT1G | TSOP-5 | V7 | Q4 | 3000 / Tape & Reel |
| NL17VHC1G07DTT1G | TSOP-5 | H7 | Q4 | 3000 / Tape & Reel |
| MC74VHC1GT07DTT1G (In Development) | TSOP-5 | TBD | Q4 | 3000 / Tape & Reel |
| NLV74VHC1G07DTT1G* | TSOP-5 | V7 | Q4 | 3000 / Tape & Reel |
| MC74VHC1G07XV5T2G (In Development) | SOT-553 | TBD | Q4 | 4000 / Tape & Reel |
| MC74VHC1GT07XV5T2G (In Development) | SOT-553 | TBD | Q4 | 4000 / Tape & Reel |
| MC74VHC1G07P5T5G (In Development) | SOT-953 | TBD | Q2 | 8000 / Tape & Reel |
| MC74VHC1GT07P5T5G (In Development) | SOT-953 | TBD | Q2 | 8000 / Tape & Reel |
| MC74VHC1G07MU1TCG (In Development) | UDFN6, 1.45 x 1.0, 0.5P | TBD | Q4 | 3000 / Tape & Reel |
| MC74VHC1GT07MU1TCG (In Development) | UDFN6, 1.45 x 1.0, 0.5P | TBD | Q4 | 3000 / Tape & Reel |
| MC74VHC1G07MU2TCG (In Development) | UDFN6, 1.2 x 1.0, 0.4P | J | Q4 | 3000 / Tape & Reel |
| MC74VHC1G07MU3TCG (In Development) | UDFN6, 1.0 x 1.0, 0.35P | TBD | Q4 | 3000 / Tape & Reel |
| MC74VHC1GT07MU3TCG (In Development) | UDFN6, 1.0 x 1.0, 0.35P | TBD | Q4 | 3000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Pin 1 Orientation in Tape and Reel

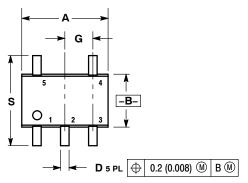
Direction of Feed

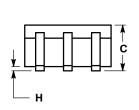


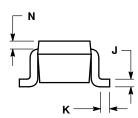
^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE L



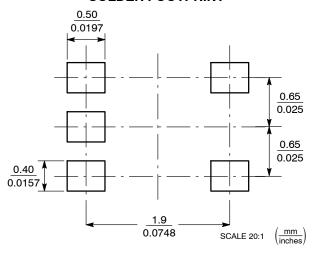




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| | INC | HES | MILLIN | IETERS | |
|-----|-----------|-------|----------|--------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 0.071 | 0.087 | 1.80 | 2.20 | |
| В | 0.045 | 0.053 | 1.15 | 1.35 | |
| C | 0.031 | 0.043 | 0.80 | 1.10 | |
| D | 0.004 | 0.012 | 0.10 | 0.30 | |
| G | 0.026 BSC | | 0.65 BSC | | |
| Н | | 0.004 | | 0.10 | |
| J | 0.004 | 0.010 | 0.10 | 0.25 | |
| K | 0.004 | 0.012 | 0.10 | 0.30 | |
| N | 0.008 REF | | 0.20 REF | | |
| S | 0.079 | 0.087 | 2 00 | 2 20 | |

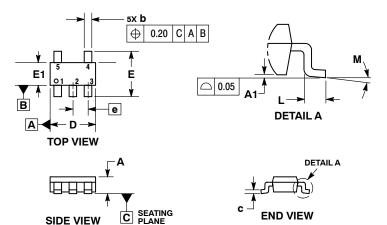
SOLDER FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

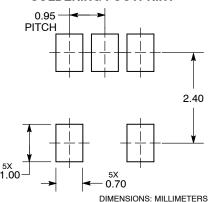
SC-74A CASE 318BQ **ISSUE B**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

| | MILLIMETERS | | |
|-----|-------------|------|--|
| DIM | MIN | MAX | |
| Α | 0.90 | 1.10 | |
| A1 | 0.01 | 0.10 | |
| b | 0.25 | 0.50 | |
| С | 0.10 | 0.26 | |
| D | 2.85 | 3.15 | |
| E | 2.50 | 3.00 | |
| E1 | 1.35 | 1.65 | |
| е | 0.95 BSC | | |
| L | 0.20 | 0.60 | |
| М | 0 ° | 10° | |

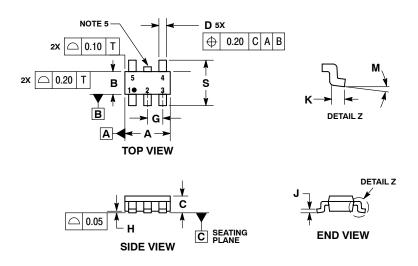
RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSOP-5 **CASE 483 ISSUE N**

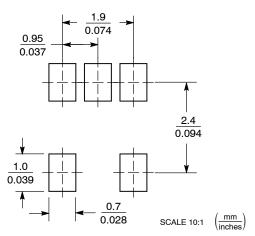


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
 OPTIONAL CONSTRUCTION: AN ADDITIONAL
- OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

| | MILLIMETERS | | |
|-----|-------------|------|--|
| DIM | MIN | MAX | |
| Α | 2.85 | 3.15 | |
| В | 1.35 | 1.65 | |
| C | 0.90 | 1.10 | |
| D | 0.25 | 0.50 | |
| G | 0.95 BSC | | |
| Н | 0.01 | 0.10 | |
| J | 0.10 | 0.26 | |
| K | 0.20 | 0.60 | |
| М | 0 ° | 10 ° | |
| S | 2.50 | 3.00 | |

SOLDERING FOOTPRINT*

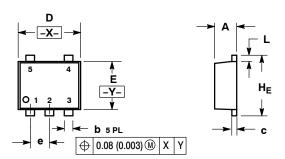


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PACKAGE DIMENSIONS

SOT-553, 5 LEAD

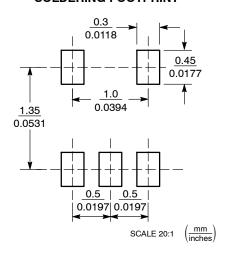
CASE 463B ISSUE C



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM
 THICKNESS OF BASE MATERIAL.

| | MILLIMETERS | | | INCHES | | |
|-----|-------------|----------|------|--------|-----------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 0.50 | 0.55 | 0.60 | 0.020 | 0.022 | 0.024 |
| b | 0.17 | 0.22 | 0.27 | 0.007 | 0.009 | 0.011 |
| С | 0.08 | 0.13 | 0.18 | 0.003 | 0.005 | 0.007 |
| D | 1.55 | 1.60 | 1.65 | 0.061 | 0.063 | 0.065 |
| E | 1.15 | 1.20 | 1.25 | 0.045 | 0.047 | 0.049 |
| е | | 0.50 BSC | | | 0.020 BSC | |
| L | 0.10 | 0.20 | 0.30 | 0.004 | 0.008 | 0.012 |
| HE | 1.55 | 1.60 | 1.65 | 0.061 | 0.063 | 0.065 |

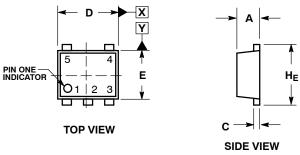
SOLDERING FOOTPRINT*

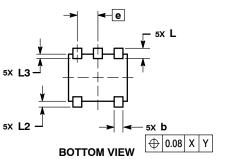


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-953 CASE 527AE ISSUE E

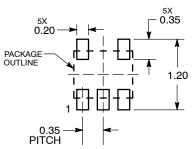




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE
- MINIMUM THICKNESS OF THE BASE MATERIAL. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| | MILLIMETERS | | | |
|-----|-------------|----------|------|--|
| DIM | MIN | NOM | MAX | |
| Α | 0.34 | 0.37 | 0.40 | |
| b | 0.10 | 0.15 | 0.20 | |
| С | 0.07 | 0.12 | 0.17 | |
| D | 0.95 | 1.00 | 1.05 | |
| E | 0.75 | 0.80 | 0.85 | |
| е | | 0.35 BSC | | |
| HE | 0.95 | 1.00 | 1.05 | |
| L | 0.175 REF | | | |
| L2 | 0.05 | 0.10 | 0.15 | |
| L3 | | | 0.15 | |

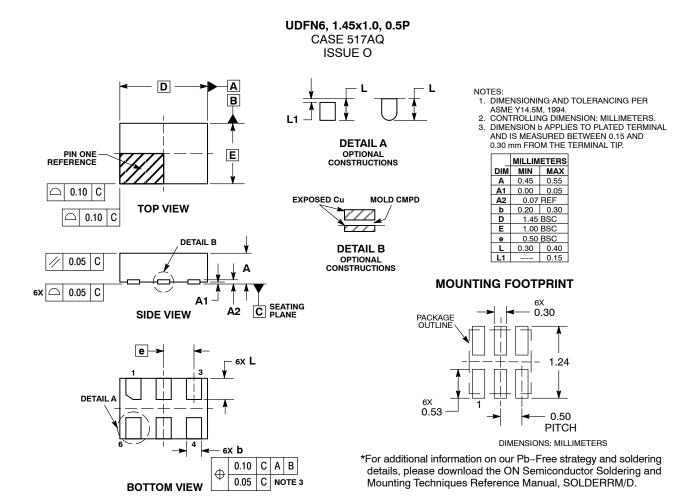
SOLDERING FOOTPRINT*



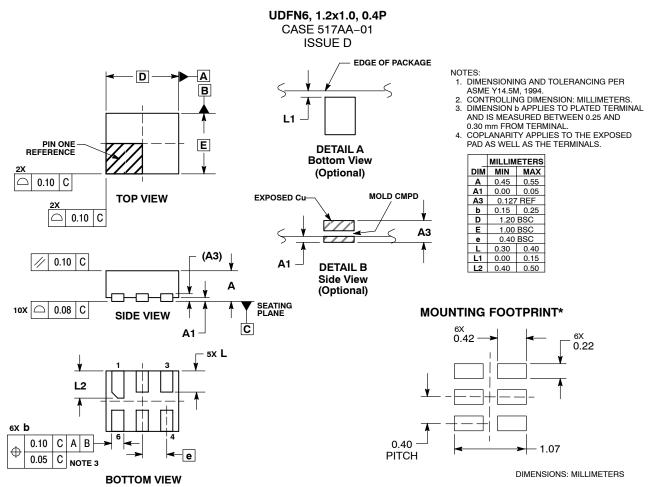
DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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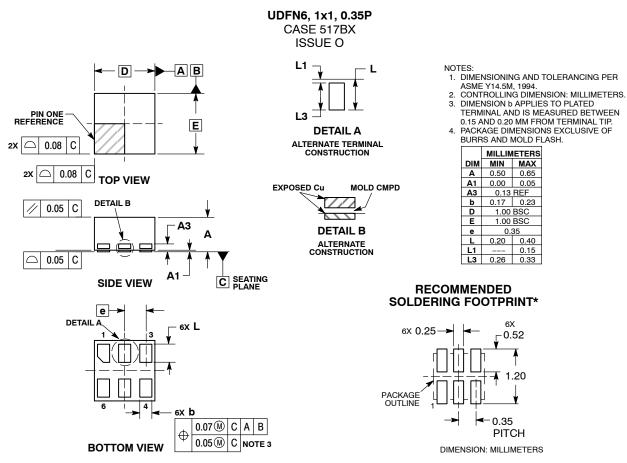


PACKAGE DIMENSIONS



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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